



**April 24-26, 2019
LAPLACE-ENSEEIH,
Toulouse, France**

CALL FOR PAPERS

INTERNATIONAL WORKSHOP ON INTEGRATED POWER PACKAGING 2019

The purpose of this workshop is to bring together researchers in the field of power electronics components, electrical insulating materials, and packaging technologies to rapidly promote the development and commercialization of high-density and high-efficiency power converters. Papers ranging from core material technologies to power converters are sought that address important challenges and present solutions to increase reliability and manufacturability of power electronic components and systems while targeting increased performance and reduced system cost. Papers are solicited in the following topics:

- System Integration And Optimization
- Compact Converter Design Techniques
- Modeling & Simulation - Components to Reliability
- Materials & Packaging Technology
- Power Semiconductor Devices / Modules
- Gate/Base Drivers
- Thermal Management & 3D Packaging
- Electromagnetic Interference
- Sensors & Protection
- High-Frequency Magnetics
- High Temperature & High Voltage Dielectrics
- Testing of Electrical Insulating Materials (e.g Space Charge and Partial Discharge Measurements)
- High-Temperature Capacitors
- Reliability Assessment & Lifetime Prediction
- Functional Safety & Product/Data Sheet Standards
- System/Component Design for Manufacturability, Compatibility with Standards, and Reliability

IWIPP COMMITTEE

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DEADLINES

Abstract Submission: November 17, 2018
Notice of Acceptance: December 16, 2018
Final Paper Submission: February 15, 2019